Multilayer Ceramic Chip Capacitors

▼ more

TDK item description ? CGA6M3X7S2A475KT****				PDF file of this page	E
Applications	Automotive Grade		2 PB PA		
Feature	Mid Mid Voltage	(100 to 630V)		Contact	
Series	CGA6(3225) [EIA 1210]		• •	Documents Catalog Update	
Status	Production		Images are for reference only and show exemplary products.	Specification	
				RoHS Certificate	
•				SVHC/REACH Certificate Update	
Size				Selection Guide for Automotive MLCC Ne	w
Length(L)		3.20mm ±0.40mm		[Promotion Video] xEV Higher Withstand Vo	oltage
Width(W)		2.50mm ±0.30mm		Applications Recommended	
Thickness(T)		2.00mm ±0.20mm		Sample Kits Characterization Sheet	
Terminal Width(B)		0.20mm Min.			
Terminal Spacing(G)				Technical Support Tools	
Recommended Land Pattern (PA)		2.00mm to 2.40mm		S-parameter	
Recommended Land Pattern (PB)		1.00mm to 1.20mm		SPICE Netlist (Simple)	
Recommended Land Pattern (PC)		1.90mm to 2.50mm		Equivalent Circuit Model	
				DC Bias/Superimpotision Model (HSPICE)	
Electrical Characterist	ics				
Capacitance		4.7µF ±10%			
Rated Voltage		100VDC			
Temperature Characteris	stic ?	X7S(±22%)			
Dissipation Factor (Max	.)	5%			
Insulation Resistance (M	/in.)	106ΜΩ			
Other					
Soldering Method		Reflow			
AEC-Q200		Yes			
Packing		Blister (Plastic)Taping [1	80mm Reel]		
Package Quantity		1000pcs			

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

Impedance	ESR
Downloaded from Arrow.com.	

CGA6M3X7S2A475K200AB	CGA6M3X7S2A475K200AB		
Configuration	Configuration		
Capacitance	DC Bias Characteristic		
CGA6M3X7S2A475K200AB	CGA6M3X7S2A475K200AB		
Configuration	Configuration		
Temperature Characteristic	Ripple Temperature Rising		
CGA6M3X7S2A475K200AB(CGA6M3X7S2A475K200AB(DC Bi No Bias) as = 50V)	CGA6M3X7S2A475K200AB(10 CGA6M3X7S2A475K200AB(50 CGA6M3X7S2A475K200AB(1 0kHz) 0kHz) MHz)		
Configuration	Configuration		

 Capacitors
 A

 Inductors (Coils)
 A

 EMC Components
 A

 Voltage / Current / Temperature Protection Devices
 A

 Ceramic Switching / Heating, Piezo Components, August and Microphones
 A

 Temporerers
 A

 Temporerers
 A

Ferrites and Accessories	>
Noise Suppressing / Magnetic Sheet	
Anechoic Chambers and Radio Wave Absorbers	
Power Supplies	
Magnets	
Flash Storages	
Wireless Power Transfer	
FA Systems	
Transparent Conductive Film	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)	
Solar Cells	
Application Specific IC (ASIC) Development and Supply	

Application Guides

Technical Support

Tech Library

Environment

Contact

News

Home

About TDK

TDK Worldwide

Terms of Use Privacy Policy Cookie Policy Counterfeit Products

Copyright(c) 2019 TDK Corporation. All rights reserved. TDK logo is a trademark or registered trademark of TDK Corporation.